SIC/XE Instruction Set Table

A整路=WORD=3byce (mord) SIC/XE向下相容SIC

SIC Instructions are in blue

東行 Szep e in blue / 最 ckar & reload Java - jav

			藍字琴為SIC	
Mnemonic	Format	Opcode		Notes
ADD m	3/4⇒Jammat	3 18	A < (A) + (mm+2)	() Abt
ADDF m	3/4 5000015	* 58	F < (F) + (mm+5)	SC X F Hook 運算
ADDR r1,r2	2 多数	90	r2 < (r2) + (r1)	SCXEX
AND m	3/4 前角網		A < (A) & (mm+2)	
CLEAR r1	2	В4	r1 < 0	X
COMP m	3/4	28	A : (mm+2)	
COMPF m	3/4	88	F : (mm+5)	X F C
COMPR r1,r2	2	A0	(r1) : (r2)	X F C
DIV m	3/4	24	A : (A) / (mm+2)	
DIVF m	3/4	64	F : (F) / (mm+5)	X F
DIVR r1,r2	2	9C	(r2) < (r2) / (r1)	X
FIX	1	C4	A < (F) [convert to integer]	X F
FLOAT	1	C0	F < (A) [convert to floating]	X F
HIO	1	F4	Halt I/O channel number (A)	PΧ
J m	3/4	3C	PC < m 無常行iump	4512496
JEQ m'	3/4	30	PC < m if CC set to =	TV ASIO
JGT m	3/4	34	PC < m if CC set to >	
JLT m A lable	3/4	38	PC < m if CC set to <	
JSUB m	3/4	48	L < (PC); PC < m	
$\sqrt{\text{LDA}}$ m	3/4	00	A < (mm+2)	1141
LDB m	3/4	68	B < (mm+2)	X
√ LDCH m	3/4	50	A [rightmost byte] < (m) 当m他首	JA 最级 Byte
LDF m	3/4	70	F < (mm+5)	X F
LDL m	3/4	80	L < (mm+2)	
LDS m	3/4	6C	$S \leftarrow (mm+2)$	X
LDT m	3/4	74	T < (mm+2)	X
LDX m	3/4	04	X < (mm+2)	
LPS m	3/4	D0	Load processor status from	PΧ
			information beginning at	
			address m (see Section	
			6.2.1)	
MUL m	3/4	20	A < (A) * (mm+2)	
MULF m	3/4	60	F < (F) * (mm+5)	X F
MULR r1,r2	2	98		X
NORM	1	C8	F < (F) [normalized]	X F
OR m	3/4	44	$A < (A) \mid (mm+2)$	/
RD m	3/4	D8	A [rightmost byte] < data	P /
			from device specified by (m)	/
RMO r1,r2	2	AC	r2 < (r1)	X
RSUB	3/4	4C	PC < (L)	<i></i>
SHIFTL r1,n	2	A4	r1 < (r1); left circular	X
			shift n bits. {In assembled	
			instruction, r2=n-1}	
SHIFTR r1,n	2	A8	r1 < (r1); right shift n	X
			bits with vacated bit	
			positions set equal to	
			leftmost bit of (r1).	
			{In assembled instruction,	
	_		r2=n-1}	
SIO	1	F0	Start I/O channel number (A);	P X
			address of channel program	
			is given by (S)	
SSK m	3/4	EC	Protection key for address m	P X
1	- 4 -	_	< (A) (see Section 6.2.4)	
√ STA m	3/4	0C	mm+2 < (A) 整整 > 整存器	寫回記憶體
STB m	3/4	78	mm+2 < (B)	X

/						
√STCH m	3/4	54	<pre>m < (A) [rightmost byte]</pre>			
STF m	3/4	80	mm+5 < (F)		X	
STI m	3/4	D4	Interval timer value <	P	X	
			(mm+2) (see Section			
			6.2.1)			
STL m	3/4	14	mm+2 < (L)			
STS m	3/4	7C	mm+2 < (S)		X	
STSW m	3/4	E8	mm+2 < (SW)	P		
STT m	3/4	84	mm+2 < (T)		X	
STX m	3/4	10	mm+2 < (X)			
SUB m	3/4	1C	A < (A) - (mm+2)			
SUBF m	3/4	5C	F < (F) - (mm+5)		X F	•
SUBR r1,r2	2	94	r2 < (r2) - (r1)		X	
SVC n	2	В0	Generate SVC interrupt. {In		X	
			assembled instruction, r1=n}			
TD m	3/4	ΕO	Test device specified by (m)	P		С
TIO	1	F8	Test I/O channel number (A)	P	X	С
TIX m	3/4	2C	X < (X) + 1; (X) : (mm+2)			С
TIXR r1	2	В8	X < (X) + 1; (X) : (r1)		X	С
WD m	3/4	DC	Device specified by (m) < (A)	P		
			[rightmost byte]			